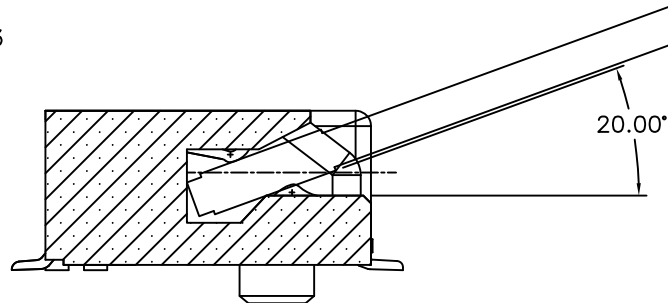
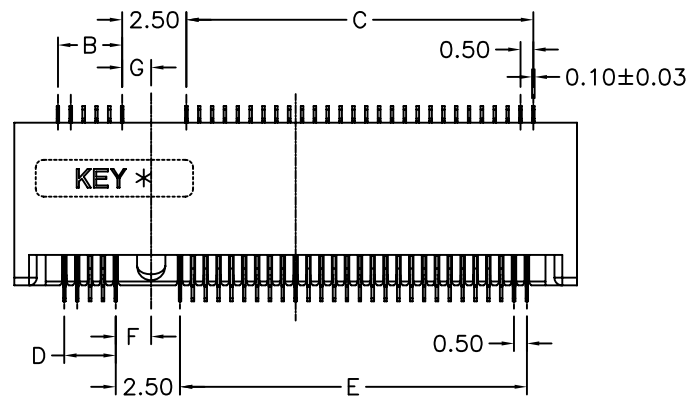


REV.	SPECIFICATION	ECN NO.	APPD.



Mating Simular
Scale 2:1

Material:

Housing: High Temperature Plastic UL94V-0, Black.

Contacts: Copper Alloy.

Solder Pad: Metal, Matte Tin Plated.

Electrical Characteristics:

Voltage Rating: AC/DC 50V.

Current Rating: 0.5 AMP.

Dielectric Withstanding Voltage: AC 300V for 1 minute.

Insulator Resistance: 500MΩ min. at DC 500V.

Contact Resistance: 55mΩ max.

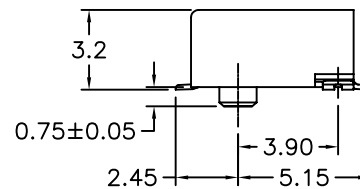
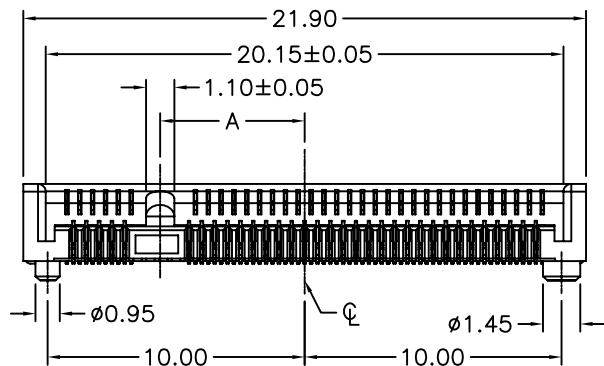
Operating Temperature: -40°C~+80°C.

Mechanical Characteristics:

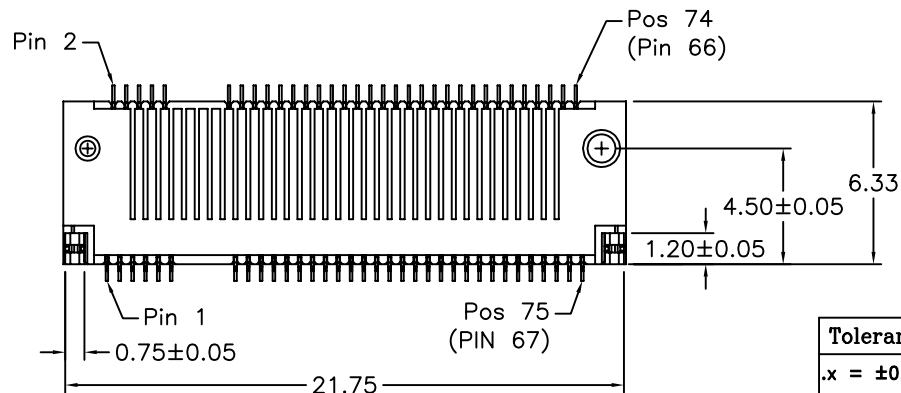
Mating Force: 2.04 kgf.

Unmating Force: 0.1 kgf.

Durability Cycles: 60 Cycles.

***RoHS Compliant**

Series	8402-	67	G	00	x	3	T
No. of Pin Count							
G: Gold Plated							
00: G/F							
							T: Tape & Reel Package
							3: 3.2mm Height
							A: Key A
							B: Key B
							E: Key E
							M: Key M



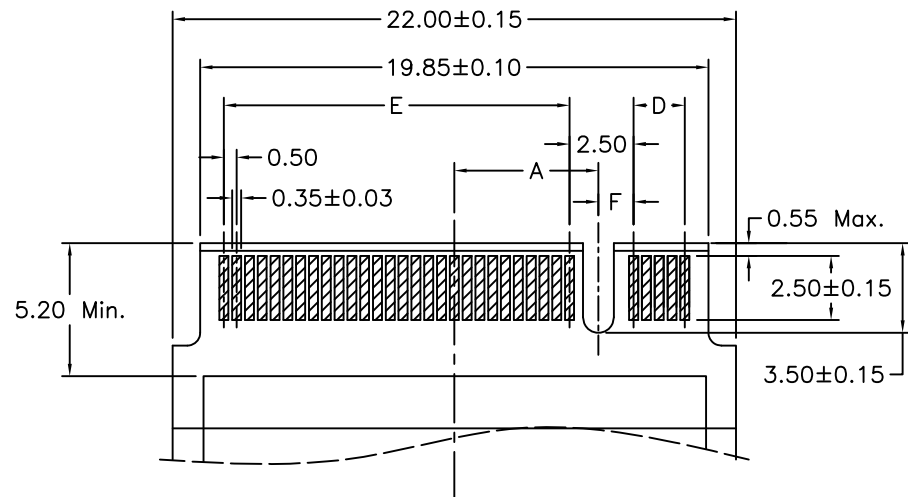
Key	Dimension							
	A	B	C	D	E	F	G	Pad Removed
A	6.625	1.5	14.5	1.0	14.5	1.375	1.125	Pos 8~15
B	5.625	2.5	13.5	2.0	13.5	1.375	1.125	Pos 12~19
E	2.625	5.5	10.5	5.0	10.5	1.375	1.125	Pos 24~31
M	-6.125	14.0	2.0	14.0	1.5	1.125	1.375	Pos 59~66

Tolerances	Dwg. No.	8402D01004	Title:
.x = ±0.25	Projection		8402 Series NGFF
.xx = ±0.15	Unit mm	Scale 1:1	
.xxx = ±0.05	Drawn By	Vic Lyu10/15'15	

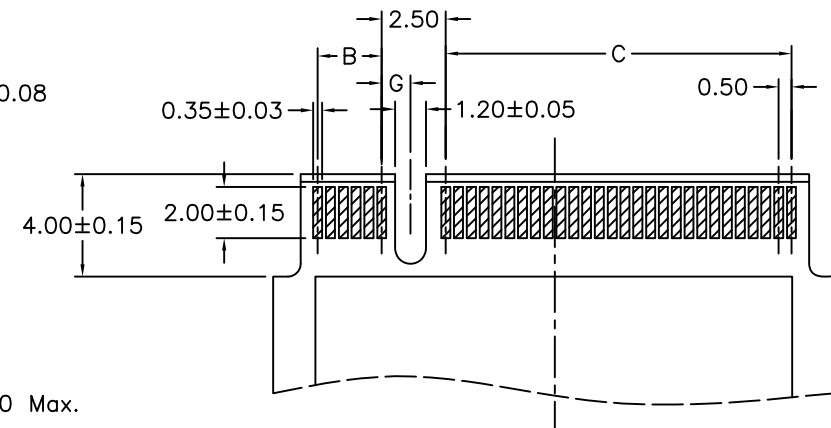
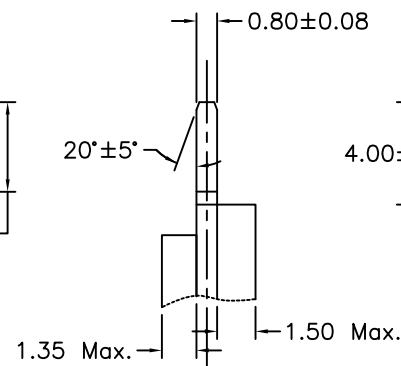
①661

OUPIN ELECTRONIC(KUNSHAN) CO., LTD.			
P/N: 8402-67G00x3T			
SHEET	1/2	Ver. No.	A2

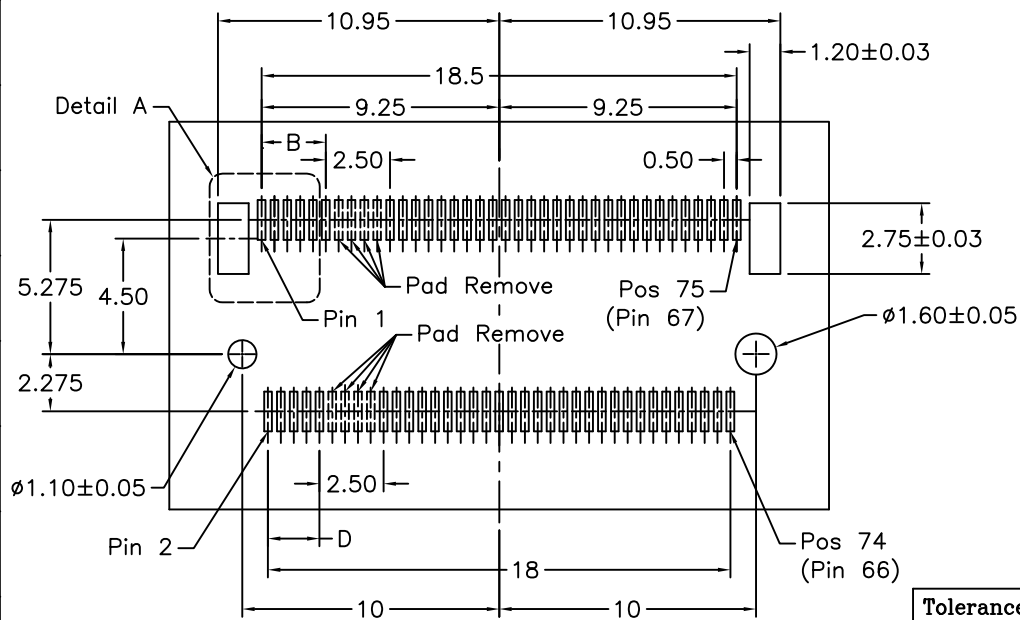
REV.	SPECIFICATION	ECN NO.	APPD.



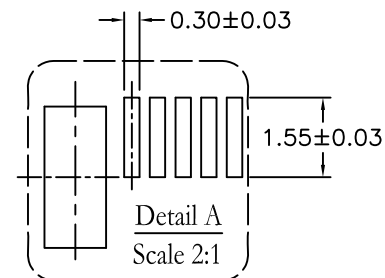
Bottom Side



Top Side



P.C. Board Layout



Key	Dimension							
	A	B	C	D	E	F	G	Pad Removed
A	6.625	1.5	14.5	1.0	14.5	1.375	1.125	Pos 8~15
B	5.625	2.5	13.5	2.0	13.5	1.375	1.125	Pos 12~19
E	2.625	5.5	10.5	5.0	10.5	1.375	1.125	Pos 24~31
M	-6.125	14.0	2.0	14.0	1.5	1.125	1.375	Pos 59~66

Tolerances	Dwg. No.	8402D01004	Title:	
.x = ±0.25	Projection			
.xx = ±0.15	Unit	mm	Scale	1:1
.xxx = ±0.05	Drawn By	Vic Lyu10/15'15	①661	

8402 Series
NGFF**OUPIN**

OUPIN ELECTRONIC(KUNSHAN) CO., LTD.

P/N: 8402-67G00x3T

SHEET 2/2 Ver. No. A2